



	Experiment title: Depth resolved strain analysis at lateral nanostructures defined by ion implantation	Experiment number: SI-787
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Report: We report on the strain analysis of a Si-wafer which was laterally patterned by focused ion-beam implantation using either a Au (dose: $2 \cdot 10^{14} \text{cm}^{-2}$) or a Ge (dose: $9 \cdot 10^{14} \text{cm}^{-2}$) source. Using a focused ion beam with a diameter of about 250nm and an energy of 70keV we produced stripes with a width of almost 300nm building up a lateral grating with a period of 550nm along the $[100]$ direction. The implanted area on the Si-wafers amounts to a size of $0.6 \times 0.6 \text{mm}^2$.

The implanted ions penetrating normal to the surface into the sample produce a large number of vacancies and interstitials which are cause a local deformation of the lattice constant. Due to the interaction of the penetrating ions with the host lattice the ion beam spread off. Therefore no sharp interfaces and a strain profil changing with depth are expected.

We studied the strain distribution of the as-implanted samples by means of X-ray grazing-incidence diffraction using the multi-purpose eight-circle diffractometer at *ID10B*. To investigate depth resolved the lateral structure of the prepared grating we measured at different incidence angles (all values in the region of the critical angle) two symmetry equivalent in-plane reflections, the strain sensitive (400) and the strain insensitive $(0\bar{4}0)$ reflection [1],[2].

In figure 1a are shown strain insensitive diffraction patterns of the Au implanted sample and in figure 2a the corresponding pattern for the Ge implanted sample. These measurements are only sensitive to the material composition. Two orders of the grating peaks can be clear identified for the Au implanted sample for the Ge implanted only one grating peak can be found which implies a more sinusoidal form of the grating. The material contrast vanishes below 200nm for both samples.

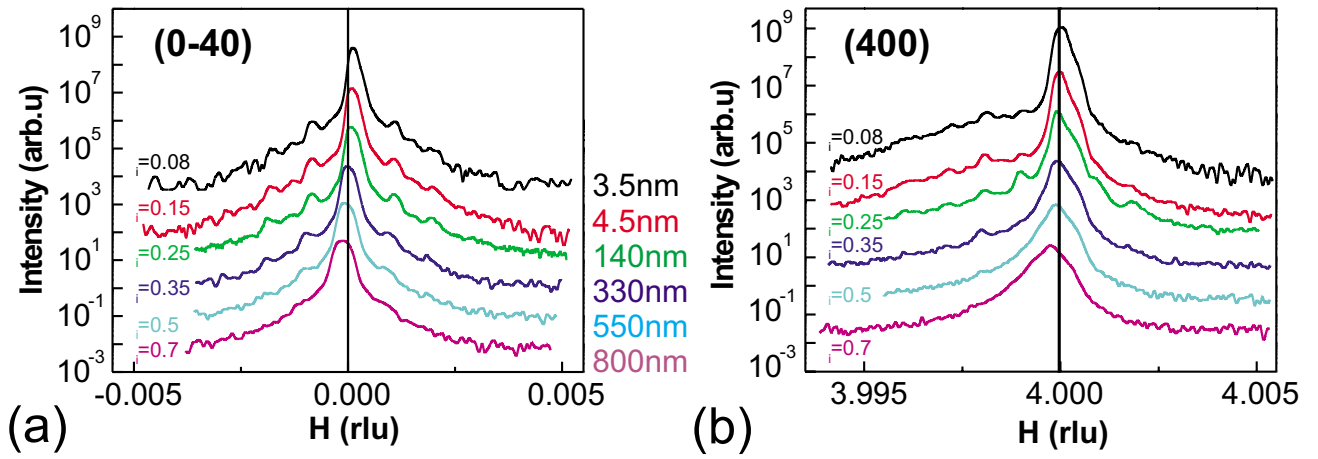


Figure 1: Strain insensitive (a) and sensitive (b) scans for the Au as-implanted sample.

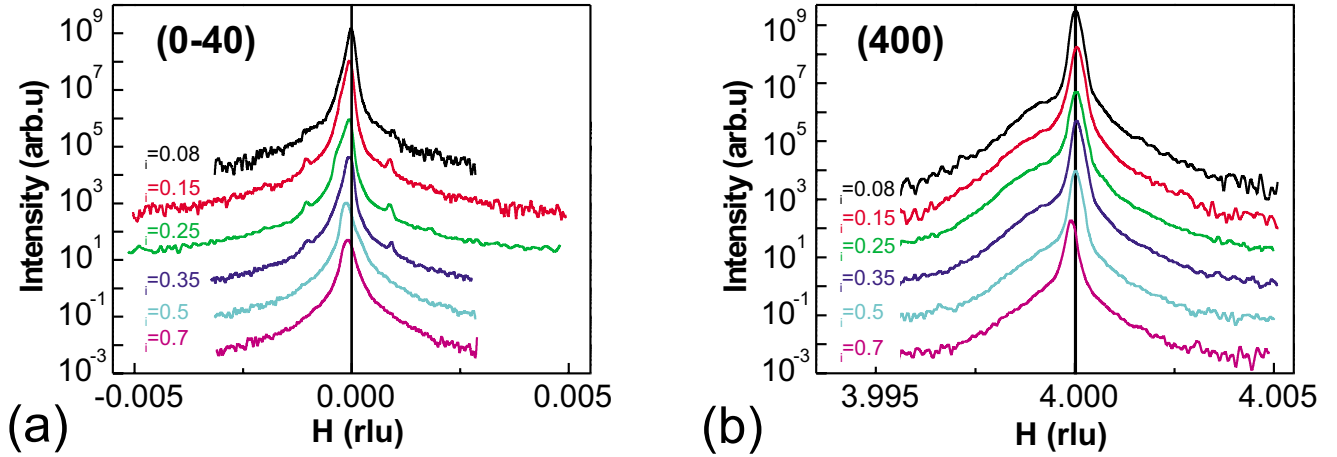


Figure 2: Strain insensitive (a) and sensitive (b) scans for the Ge as-implanted sample.

In figure 1b are shown strain sensitive diffraction patterns of the Au implanted sample and in figure 2b the corresponding pattern for the Ge implanted sample. Whereas for the Au implanted sample a strain modulation can be clearly identified we found no clear modulation for the Ge implanted sample. In both samples we found at the surface (depth: 3.5nm) a tensile residual strain corresponding to the implanted dose we found a value of $-3.5 \cdot 10^{-4}$ for Au sample and $-1 \cdot 10^{-4}$ for the Ge sample. Below a depth of 350nm the residual strain is almost zero (detection limit: $< 2 \cdot 10^{-5}$) and in the diffraction pattern of the Au sample almost no grating peaks were observed. The samples behaved differently at larger penetration depths whereas the Au sample showed with increasing penetration depth an increasing FWHM of the (400) substrate reflection (from $2.1 \cdot 10^{-4}@3\text{nm}$) to $5.5 \cdot 10^{-4}@800\text{nm}$) which was accompanied by a small increase of the lateral lattice constant of about $< 0.01\%$. We found an almost constant FWHM of about $1.5 \cdot 10^{-4}$ and starting at a penetration depth of about 800nm a pronounced (due to the smaller FWHM) increase of the lateral lattice constant of about 0.015% indicating a high lattice quality of the formed surface grating.

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References

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